

# **ELEN E3106/4106 Lecture 14**

## **p-n Junction Breakdown and Narrow Base Diodes Outline**

- Zener breakdown
- Avalanche breakdown
- Punch-through breakdown
- Narrow—base diodes

### **Assignments:**

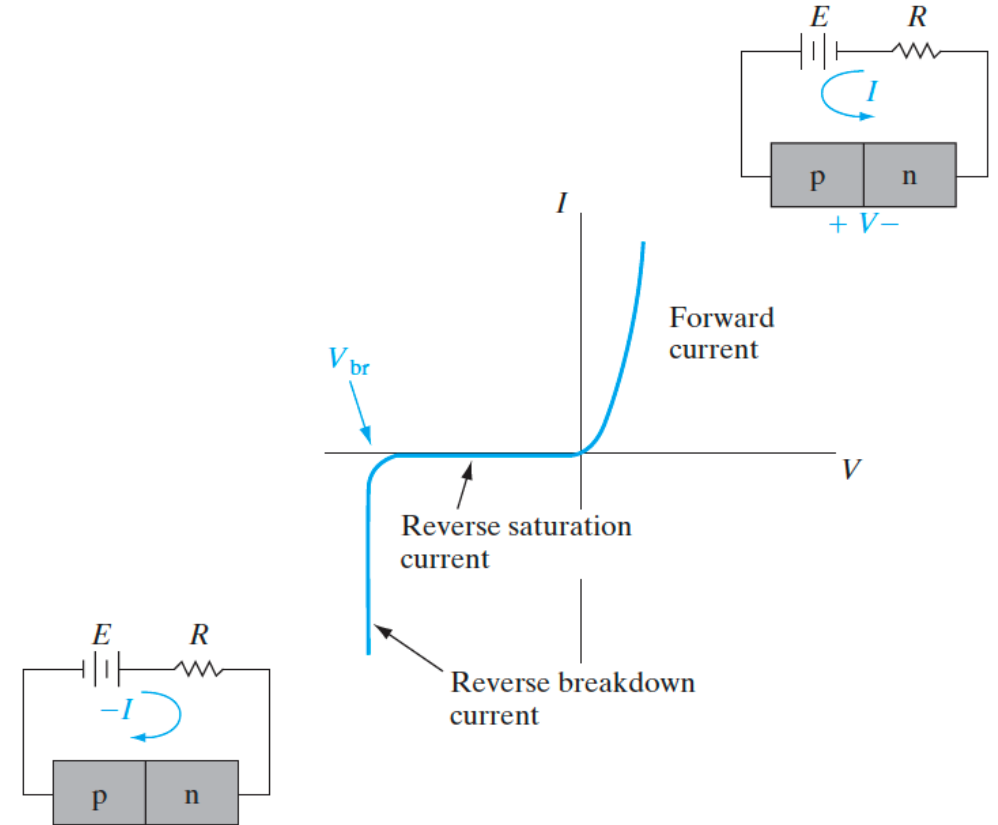
Reading: Streetman and Banerjee §5.4  
Homework 6 due Friday Oct. 24<sup>th</sup> by 5pm  
Exam 2 Tuesday Oct. 28<sup>th</sup>

# Recap of p-n Junctions

- We've (nearly) exhausted the p-n junction. Now we know:
  - 1) Why and how it conducts current (\_\_\_\_\_, reverse)
  - 2) How to calculate depletion width \_\_\_\_\_, field, built-in voltage \_\_\_\_\_
  - 4) How diodes store charge as capacitors in \_\_\_\_\_ (we have not discussed FB capacitance)
  - 5) How to make optoelectronics based on photodiodes (solar cells, \_\_\_\_\_, LEDs & lasers)
- Today, we have 2 final topics before we get to BJTs!
  - 6) How diodes break down
  - 7) Narrow-base diodes

# Reverse-bias Breakdown

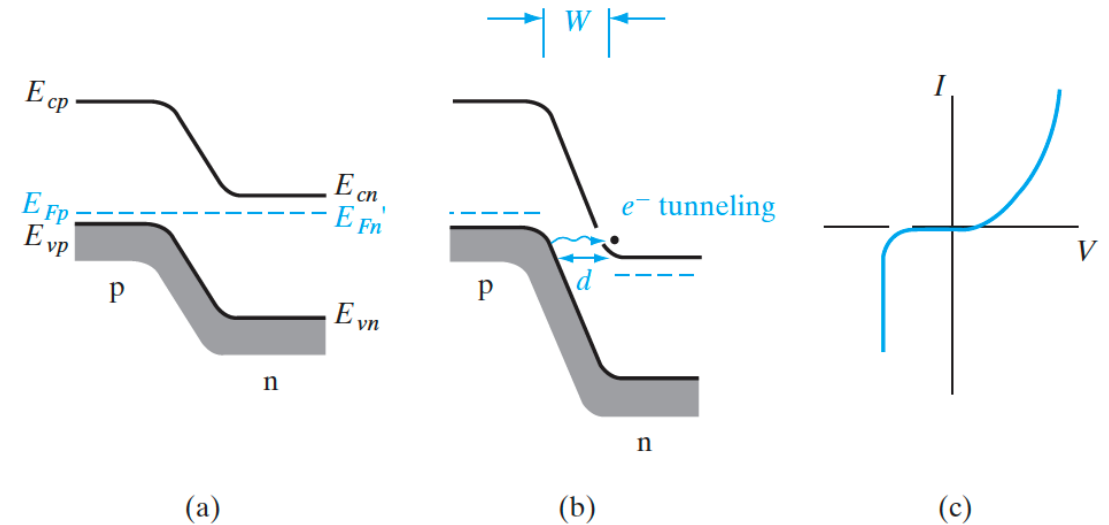
- Recall: so far we have found that p-n junction in \_\_\_\_\_ has a small, essentially \_\_\_\_\_ reverse saturation current, \_\_\_\_\_
- This is true until we reach a critical high reverse bias point, called the \_\_\_\_\_
- We can vary  $V_{br}$  through choice of \_\_\_\_\_ concentrations
- What happens at  $V_{br}$ ? Reverse current sharply \_\_\_\_\_, and relatively large currents can flow with little increase in RB
- Is breakdown reversible?



# Zener Breakdown

- Dominant for heavily doped junctions ( $> \text{_____} \text{cm}^{-3}$ )
- Dominant at \_\_\_\_\_ (up to a few volts)
- With narrow barrier in RB, tunneling of e- from p-side filled states in \_\_\_\_\_ to n-side empty states in \_\_\_\_\_ can occur
- Tunneling distance \_\_\_\_\_ becomes smaller with RB as E-field creates \_\_\_\_\_ for band edges
- Prevalent in heavily doped \_\_\_\_\_ junction
  - W must only extend \_\_\_\_\_ into each side of junction
  - We are assuming W does not increase very much with \_\_\_\_\_ so  $d$  can become small (accurate for \_\_\_\_\_ and heavy doping on both sides)

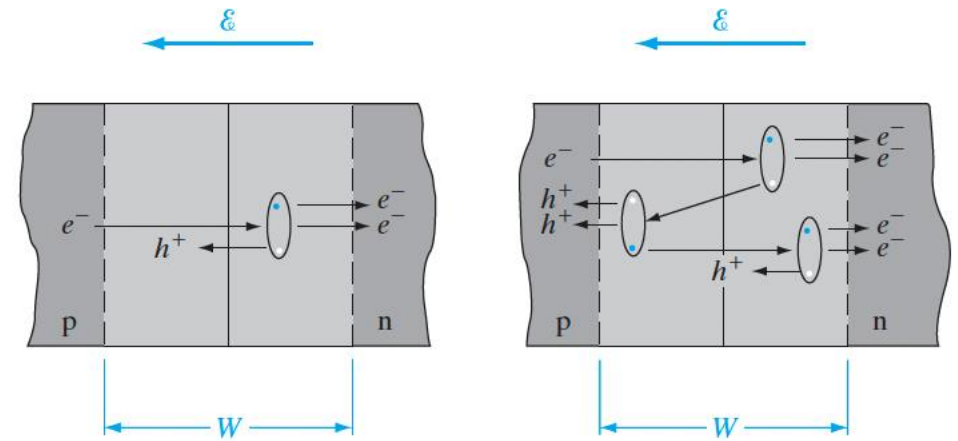
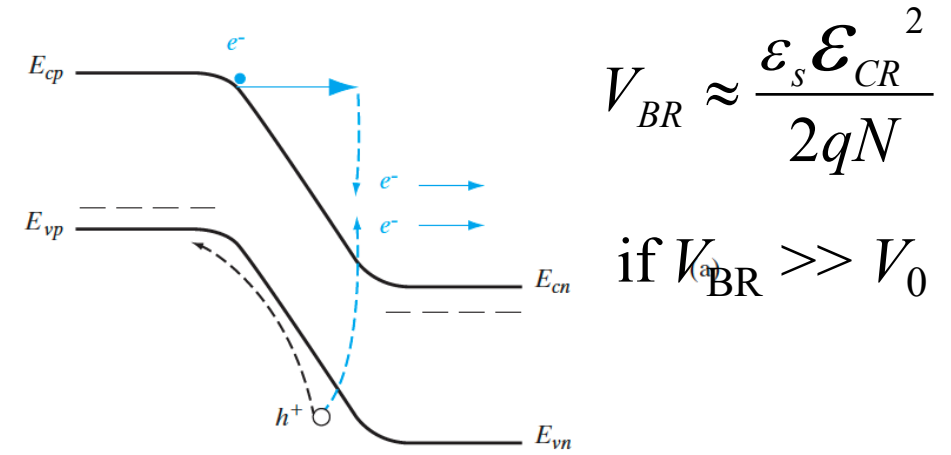
(a) Heavily doped junction at equilibrium, (b) reverse bias with e-tunneling from p to n, (c) I-V characteristic



$$V_{BR} = \frac{\epsilon_s \mathcal{E}_{CR}^2}{2qN} - V_0 \quad \mathcal{E}_{CR} \approx 10^6 \text{ V/cm}$$

# Avalanche Breakdown

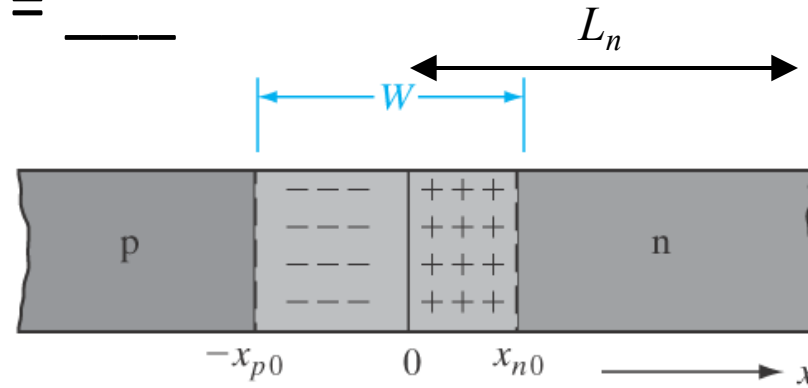
- Dominant for more lightly doped (\_\_\_\_\_  $cm^{-3}$ ) junctions
- Because the depletion region is \_\_\_\_\_, e- accelerated across it will gain enough \_\_\_\_\_ to cause an \_\_\_\_\_ collision with the lattice, generating EHP
  - Called \_\_\_\_\_
- The original e- and newly generated e- are both swept to \_\_\_\_\_, while h+ is swept to \_\_\_\_\_ --> carrier \_\_\_\_\_
- Multiplication can become high if there are many impact ionization events: imagine incoming e-generated EHP, each of these carriers created additional EHPs through impact ionization, and so on
- This \_\_\_\_\_ process causes reverse current to increase



(a) EHPs created by impact ionization, (b) band diagram showing primary e- gaining KE in depletion region, creating secondary EHPs (c) Primary, secondary, and tertiary collisions

# Punch-through Breakdown

- Occurs when either depletion region “\_\_\_\_\_” the entire length of the diode, e.g.  $x_n(V) = \text{_____}$



- An issue for \_\_\_\_\_, \_\_\_\_\_ regions
  - Recall:  $W$  extends primarily into lightly doped side, as  $W$  increases with RB (\_\_\_\_\_) it can fill the entire length!

$$W = x_n + x_p = \sqrt{\frac{2\epsilon_s}{q} \left( \frac{1}{N_A} + \frac{1}{N_D} \right) (V_0 - V)}$$

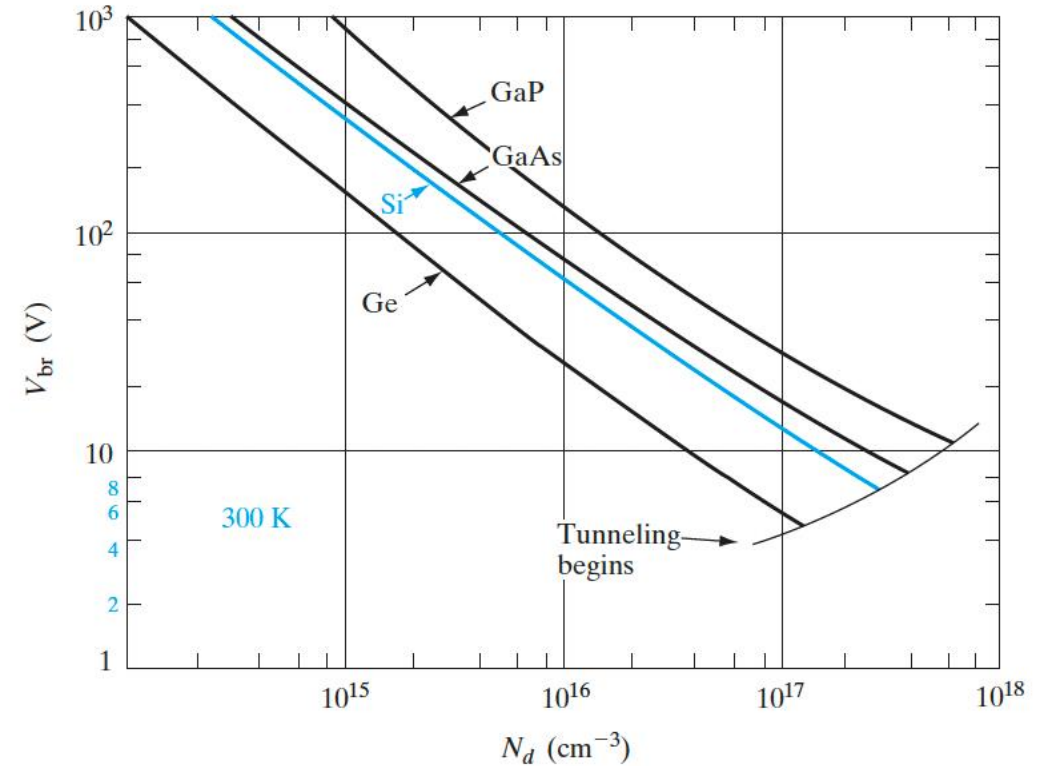
- Result: Breakdown below the value of  $V_{br}$  predicted by zener or avalanche breakdown

# Empirical Observations on Breakdown

- $V_{br}$  decreases with \_\_\_\_\_ doping,  $N$
- $V_{br}$  decreases with \_\_\_\_\_  $E_g$

What about temperature?

- For tunneling (Zener) breakdown,  $|V_{br}| \sim$



- For avalanche breakdown,  $|V_{br}|$

## Problem: Avalanche breakdown

A Ge p+n junction diode has donor doping of  $2 \times 10^{15} \text{ cm}^{-3}$  and relative permittivity 16. What will be the minimum thickness of n region that will ensure avalanche breakdown at 300 V reverse bias voltage?

$$N_d = 2 \times 10^{15} \text{ cm}^{-3}$$

$$x_{n0} = \frac{W}{1 + \frac{N_d}{N_a}}$$

For p+n junction,  $N_a \gg N_d$ , so  $\frac{N_d}{N_a} \ll 1$  and  $1 + \frac{N_d}{N_a} \approx 1$  so  $x_{n0} \approx W$

$$W = \sqrt{\frac{2\epsilon}{q} \left( \frac{1}{N_a} + \frac{1}{N_d} \right) (V_0 - V)} \approx \sqrt{\frac{2\epsilon}{q} \left( \frac{1}{N_d} \right) (V_{br})}$$

$$x_{n0} = W = \sqrt{\frac{2(16)(8.85 \times 10^{-14})}{(1.6 \times 10^{-19})} \left( \frac{1}{2 \times 10^{15}} \right) (300)}$$

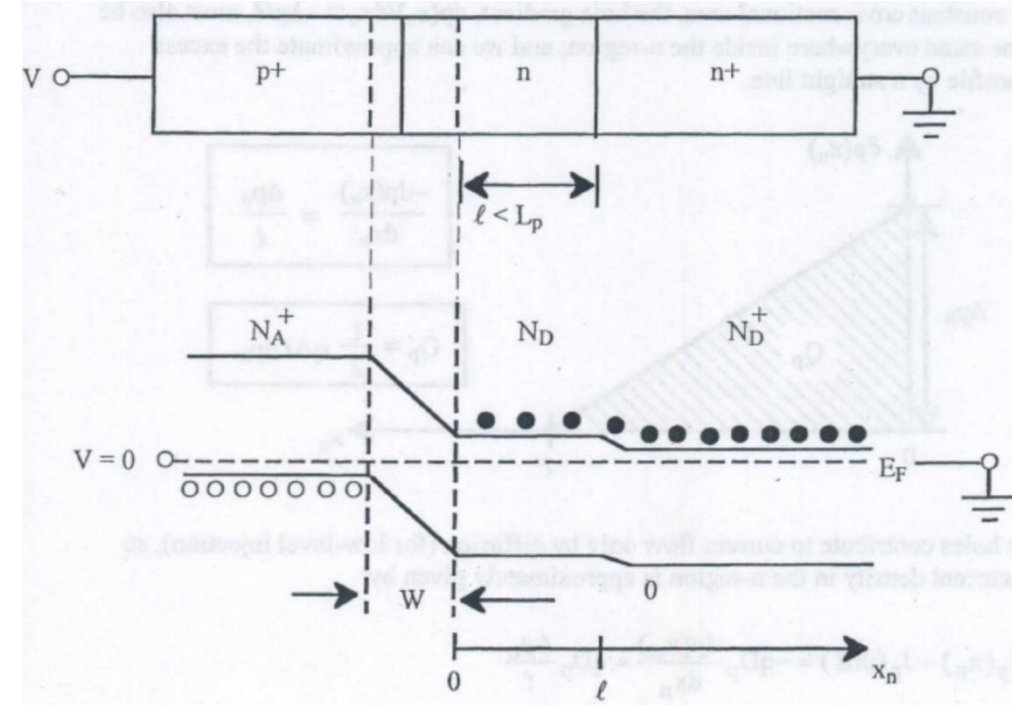
$$x_{n0} = 1.5 \text{ microns}$$

This is the 1.5 microns thickness that will ensure avalanche breakdown rather than punch-through.



# Narrow Base Diode

- Before we begin our discussion of BJTs, we need to discuss the narrow-base p-n diode
- The typical minority carrier diffusion length in Si is  $\sim$  \_\_\_\_\_
- But modern device lengths are very small, on the order of \_\_\_\_\_
- This can easily create situations where \_\_\_\_\_ < \_\_\_\_\_
  - Ex. Let's imagine we have a p<sup>+</sup>-n diode with an n region width  $l$  less than the hole diffusion length
- This is called a \_\_\_\_\_

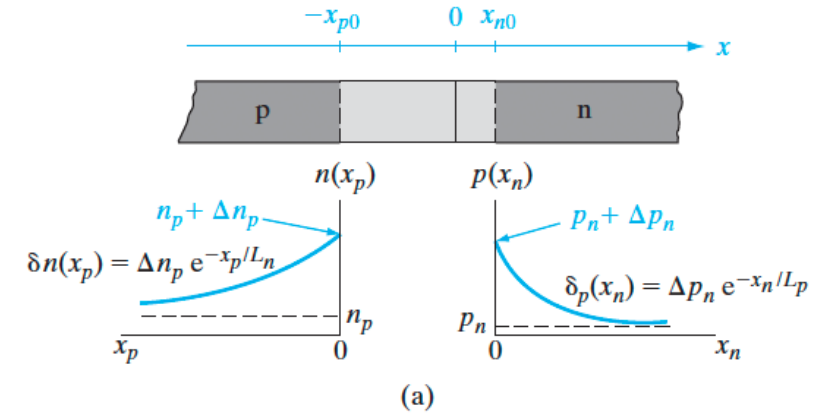


## Excess Minority Carrier Spatial Distributions

- Recall our discussion on the long base diode (\_\_\_\_\_ decay):

$$\delta n(x_p) = \Delta n_p e^{-x_p/L_n} = n_p(e^{qV/kT} - 1)e^{-x_p/L_n}$$

$$\delta p(x_n) = \Delta p_n e^{-x_n/L_p} = p_n(e^{qV/kT} - 1)e^{-x_n/L_p}$$



- But instead of “long” ( $l > L_p$ ) exponential decay:

$$\delta p(x) = \Delta p_{n0} e^{-\frac{x}{L_p}} = \frac{n_i^2}{N_d} \left( e^{\frac{qV}{kT}} - 1 \right) e^{-x/L_p}$$

- We have the “narrow” or “short” ( $l < L_p$ ) approximation (\_\_\_\_\_ approximation):

$$\delta p(x) = \Delta p_{n0} \left( 1 - \frac{x}{l} \right) = \frac{n_i^2}{N_d} \left( e^{\frac{qV}{kT}} - 1 \right) \left( 1 - \frac{x}{l} \right)$$

- We can think of the (metal) contacts at the end of the p-n junction \_\_\_\_\_.  
Note the diode is too narrow (short) for any hole recombination in n-region, so recombination happens at the contact, setting the boundary conditions:

$$\delta p(x = l) = 0$$

$$\delta p(x = x_n) = \Delta p_n = p_n(e^{\frac{qV}{kT}} - 1)$$

# Current in Narrow Base Diode

- Total injected ( ) minority charge at FB is the area under the triangle. Remember excess carrier distribution is a function of distance:

$$Q_p = \frac{1}{2} q \Delta p (Al) = \frac{1}{2} q Al \frac{n_i^2}{N_D} (e^{qV/kT} - 1)$$

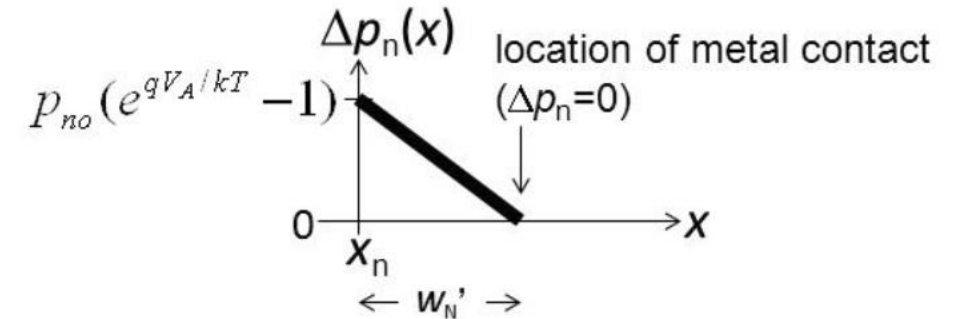
- The hole concentration gradient using the straight approximation:

$$\frac{dp}{dx} = \frac{-\Delta p_n}{l}$$

- Assuming . injection, hole diffusion current can be written:

$$J_p = -q D_p \left( \frac{dp}{dx} \right) = -q D_p \frac{-\Delta p_n}{l} = \frac{q D_p}{l} \left( \frac{n_i^2}{N_D} \right) (e^{qV/kT} - 1)$$

- Compare with “long” diode diffusion current:  $J_p = q \frac{D_p}{L_p} \frac{n_i^2}{N_D} (e^{qV/kT} - 1)$



# Current in Narrow Base Diode

- $l$  \_\_\_\_\_  $L_p$  in the denominator of the diode equation since  $l \ll L_p$
- Because of constant gradient (\_\_\_\_\_),  $J_p$  is constant in narrow QNR because no holes are lost due to \_\_\_\_\_ as they diffuse to the metal contact!
- Shorter QNR  $\rightarrow$  steeper concentration gradient  $\rightarrow$  \_\_\_\_\_ current in narrow base diode than "long" diode for the same voltage
- Total diode current if:
  - It's a  $p^+-n$  ( $N_A \gg N_D$ ) diode:  $J = J_p$
  - It's a  $p-n$  ( $N_A \sim N_D$ ) diode:  $J = J_p + J_n$

